12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20140212002
Qualification of copper wire as alternate bonding material for selected products in VSSOP Package
Final Change Notification

Date: 2/17/2014
To: MOUSER PCN

Dear Customer:

This is a final announcement of change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

The changes discussed within this PCN will not take effect any earlier than **30** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140212002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM7322MM/NOPB	LM7322MM/NOPB
LM7322MME/NOPB	LM7322MME NOPB
LM7322MME/NOPB	LM7322MME/NOPB
LM7332MM/NOPB	LM7332MM/NOPB
LM7332MME/NOPB	LM7332MME NOPB
LM7332MME/NOPB	LM7332MME/NOPB
LM8262MM/NOPB	LM8262MM/NOPB
LM8272MM	null
LM8272MM/NOPB	LM8272MM NOPB
LM8272MM/NOPB	LM8272MM/NOPB
LMC555CMM/NOPB	LMC555CMM/NOPB
LMC6035IMM	LMC6035IMM
LMC6482IMM	LMC6482IMM
LMC6772AIMM	null
LMC8101MM/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140212002	**PCN Date:**	02/17/2014

Title:	Qualification of copper wire as alternate bonding material for selected products in VSSOP Package

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	03/17/2014	**Estimated Sample Availability:**	02/17/2014

Change Type:

☐	Assembly Site	☒	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part Number Change		

PCN Details

Description of Change:

To qualify Cu wire as alternative bond material for selected products in VSSOP package. Most of the devices in this notification were included in Forecast PCN20125301A published on July 31, 2012 which was issued from the National Semiconductor PCN system.

	From	To
Wire	Au, 0.9mil & 1.0mil	Cu, 1 mil or Au, 0.9mil & 1.0mil

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None

Product Affected:

LM7322MM/NOPB	LM8262MM/J7001401	LM8272MM	LMC6035IMM
LM7322MME/NOPB	LM8262MM/J7001401	LM8272MM/NOPB	LMC6482IMM
LM7322MMX/NOPB	LM8262MM/NOPB	LM8272MMX/NOPB	LMC6482IMMX
LM7332MM/NOPB	LM8262MMX/J7001402	LMC555CMM	LMC6772AIMM
LM7332MME/NOPB	LM8262MMX/J7001402	LMC555CMM/NOPB	LMC8101MM
LM7332MMX/NOPB	LM8262MMX/NOPB	LMC555CMMX	LMC8101MM/NOPB
LM8262MM			

Qualification Data: Approved November, 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LMC6482IMM/NOPB (MSL 1-260c)

Package Construction Details

Assembly Site:	TIEM	Mold Compound:	4209002
# Pins-Designator, Family:	8-DGK, VSSOP	Mount Compound:	8080598
Leadframe (Finish, Base):	Matte Sn, Cu	Bond Wire:	1 Mil Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**Autoclave 121C	121C, 2 ATM (96 hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0

Notes: **Tests received preconditioning sequence: MSL1-260C

Reference Qualification Data: Approved October, 2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LMC6482AIM/NOPB (MSL 1-260c)

Package Construction Details

Assembly Site:	TIEM	Mold Compound:	4209002
# Pins-Designator, Family:	8-D, SOIC	Mount Compound:	8080598
Leadframe (Finish, Base):	Matte Sn, Cu	Bond Wire:	1 Mil Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0

Notes: **Tests received preconditioning sequence: MSL1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com